## **MICROWAVE POWER GaAs FET**

### Internally Matched Power GaAs FETs (X, Ku-Band)

#### **Features**

- High power
  - $P_{1dB}$  = 37.5 dBm at 9.5 GHz to 10.5 GHz
- High gain
- G<sub>1dB</sub> = 7.0 dB at 9.5 GHz to 10.5 GHz
  Broadband internally matched
- Hermetically sealed package

### RF Performance Specifications ( $T_a = 25^{\circ}C$ )

Characteristic	Symbol	Condition	Unit	Min.	Тур.	Max.
Output Power at 1dB Compression Point	P <sub>1dB</sub>	V <sub>DS</sub> = 9V f = 9.5 - 10.5 GHz	dBm	37.0	37.5	-
Power Gain at 1dB Compression Point	G <sub>1dB</sub>		dB	6.0	7.0	-
Drain Current	I <sub>DS</sub>		Α	-	2.0	2.5
Power Added Efficiency	$\eta_{add}$		%	-	20	-
Channel-Temperature Rise	$\Delta T_{ch}$	V <sub>DS</sub> x I <sub>DS</sub> x R <sub>th (c-c)</sub>	°C	-	-	80

### Electrical Characteristics (T<sub>a</sub> = 25°C)

Characteristic	Symbol	Condition	Unit	Min.	Тур.	Max.
Transconductance	gm	V <sub>DS</sub> = 3V I <sub>DS</sub> = 2.4A	mS	-	1400	-
Pinch-off Voltage	V <sub>GSoff</sub>	V <sub>DS</sub> = 3V I <sub>DS</sub> = 72 mA	V	-2	-3.5	-5
Saturated Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> = 3V V <sub>GS</sub> = 0V	Α	-	5.0	5.7
Gate-Source Breakdown Voltage	V <sub>GSO</sub>	I <sub>GS</sub> = -72 μA	V	-5	-	-
Thermal Resistance	R <sub>th (c-c)</sub>	Channel to Case	°C/W	-	3.0	3.7

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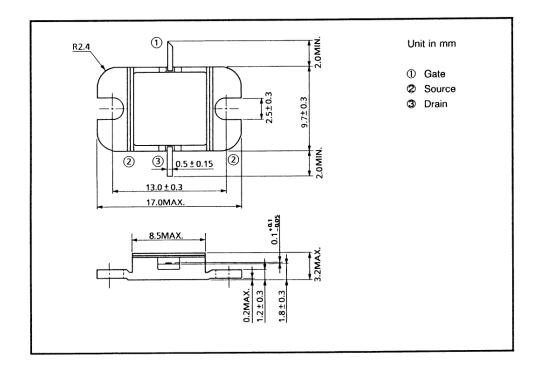
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The information contained here is subject to change without notice.

# Absolute Maximum Ratings ( $T_a = 25^{\circ}C$ )

Characteristic	Symbol	Unit	Rating
Drain-Source Voltage	V <sub>DS</sub>	V	15
Gate-Source Voltage	V <sub>GS</sub>	V	-5
Drain Current	I <sub>D</sub>	Α	5.7
Total Power Dissipation (T <sub>c</sub> = 25°C)	P <sub>T</sub>	W	30
Channel Temperature	T <sub>ch</sub>	°C	175
Storage Temperature	T <sub>stg</sub>	°C	-65 ~ 175

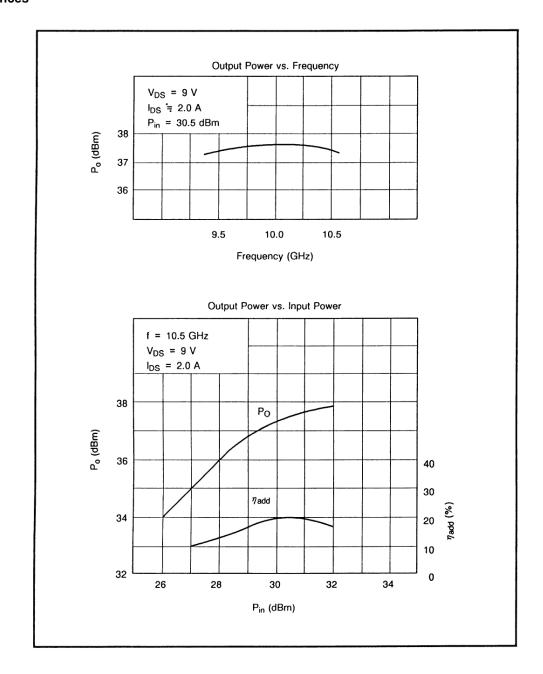
### Package Outline (2-9D1B)



## **Handling Precautions for Packaged Type**

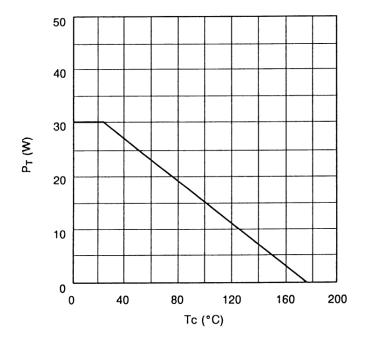
Soldering iron should be grounded and the operating time should not exceed 10 seconds at 260°C.

#### **RF Performances**



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# **Power Dissipation vs. Case Temperature**



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